

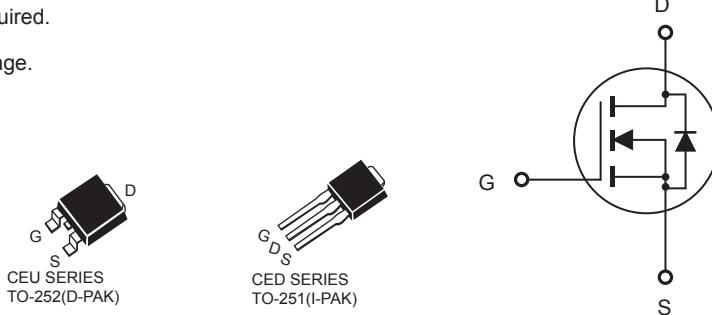


CED01N65A/CEU01N65A

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 650V, 0.9A, $R_{DS(ON)} = 15\Omega$ @ $V_{GS} = 10V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current-Continuous	I_D	0.9	A
Drain Current-Pulsed ^a	I_{DM}	3.6	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	P_D	43 0.35	W W/ $^\circ C$
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	R_{JC}	3.5	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	R_{JA}	50	$^\circ C/W$



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 0.4\text{A}$		12	15	Ω
Dynamic Characteristics^c						
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_D = 0.4\text{A}$		1		S
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		165		pF
Output Capacitance	C_{oss}			60		pF
Reverse Transfer Capacitance	C_{rss}			30		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 300\text{V}, I_D = 0.4\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 4.7\Omega$		10	20	ns
Turn-On Rise Time	t_r			11	22	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			21	42	ns
Turn-Off Fall Time	t_f			42	84	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 480\text{V}, I_D = 0.8\text{A}, V_{\text{GS}} = 10\text{V}$		10	13	nC
Gate-Source Charge	Q_{gs}			0.7		nC
Gate-Drain Charge	Q_{gd}			7		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				0.8	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 0.8\text{A}$			1.5	V
Notes :						
a.Repetitive Rating : Pulse width limited by maximum junction temperature. ^d						
b.Device Mounted on FR4 Board, $t < 10 \text{ sec.}$ ^e						
c.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$. ^f						
d.Guaranteed by design, not subject to production testing. ^g						
^e						



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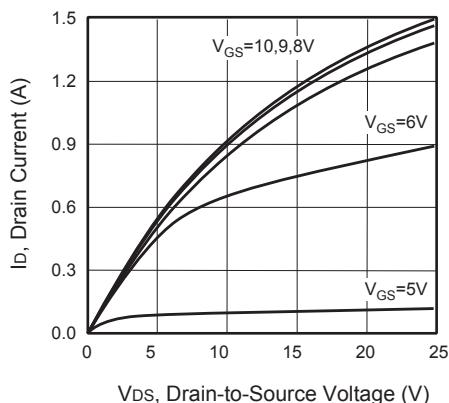


Figure 1. Output Characteristics

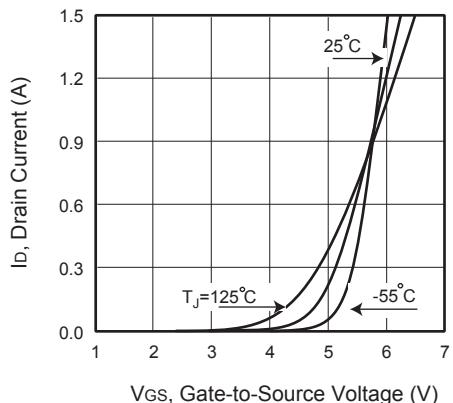


Figure 2. Transfer Characteristics

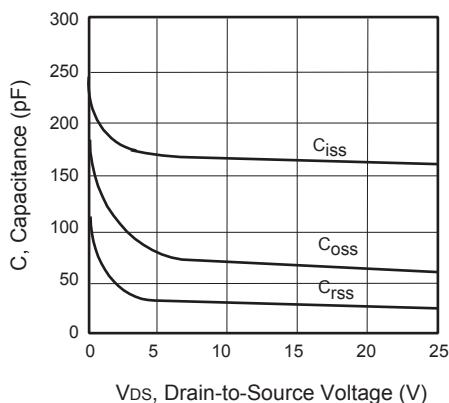


Figure 3. Capacitance

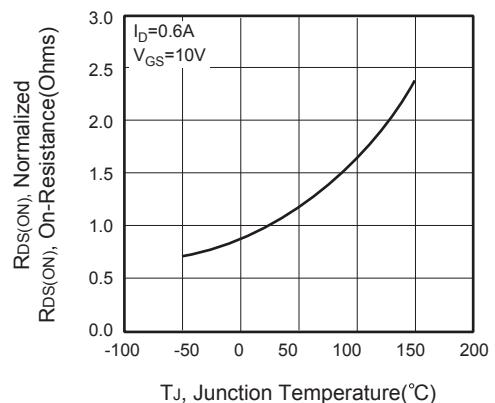


Figure 4. On-Resistance Variation with Temperature

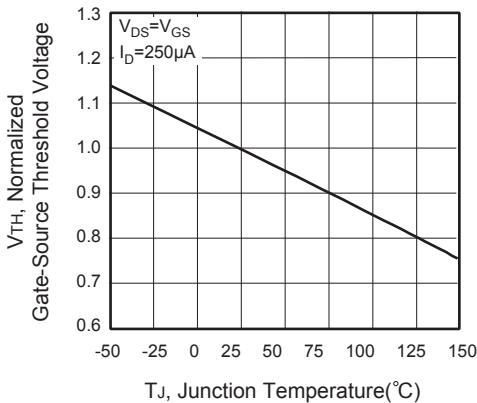


Figure 5. Gate Threshold Variation with Temperature

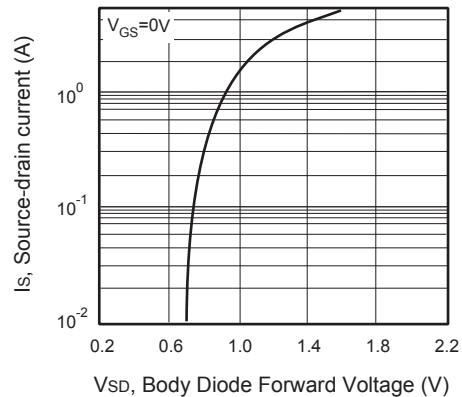


Figure 6. Body Diode Forward Voltage Variation with Source Current



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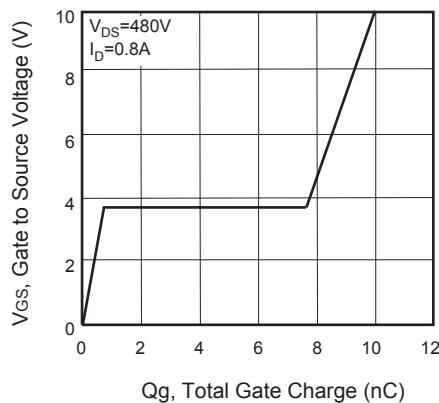


Figure 7. Gate Charge

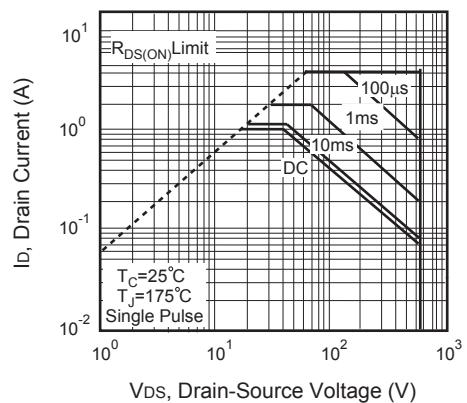


Figure 8. Maximum Safe Operating Area

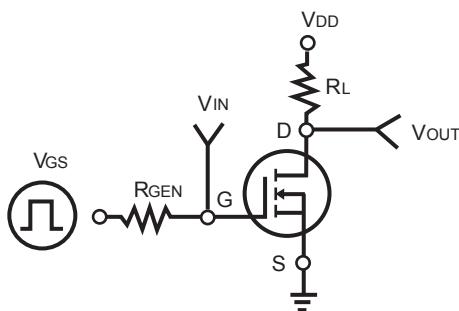


Figure 9. Switching Test Circuit

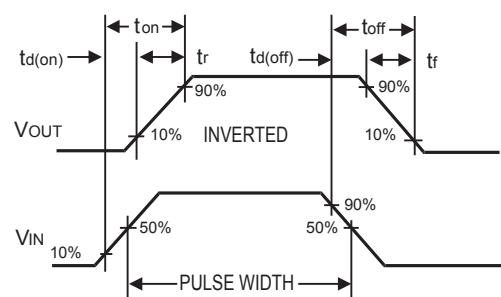


Figure 10. Switching Waveforms

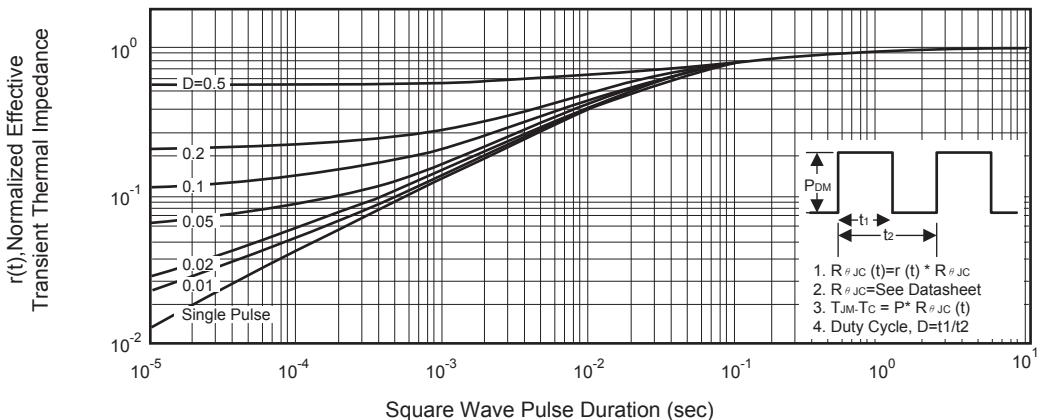


Figure 11. Normalized Thermal Transient Impedance Curve